

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

|                           |   |                      |
|---------------------------|---|----------------------|
| In re Application of:     | § |                      |
| Sun et al.                | § |                      |
|                           | § | Group Art Unit: 1753 |
| Serial No.: 10/616,097    | § |                      |
|                           | § |                      |
| Confirmation No.: 1645    | § |                      |
|                           | § | Examiner: Edna Wong  |
| Filed: July 8, 2003       | § |                      |
|                           | § |                      |
| For: Multiple-Step        | § |                      |
| Electrodeposition Process | § |                      |
| for Direct Copper Plating | § |                      |
| on Barrier Materials      | § |                      |

MAIL STOP RCE  
 Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

Dear Sir:

**RESPONSE ACCOMPANYING REQUEST FOR CONTINUED EXAMINATION**

In response to the Final Office Action dated February 28, 2007 having a shortened statutory period for response set to expire on May 28, 2007, please enter this response accompanying the Request for Continued Examination (RCE), and reconsider the claims pending in the application for the reasons discussed below. The Applicants believe that RCE fee of \$790.00, one month extension fee and excess claim fee are due in connection with this response and has been paid with the submission of this paper using the Patent Electronic Business Center. The Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782 for any other fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.